



Designing a multi-chiplet manycore system using the POPSTAR optical NoC architecture (invited)

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Designing a multi-chiplet manycore system using the POPSTAR optical NoC architecture

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CEA-List

► Silicon Photonics moves forward for long distance optical wireline transceiver

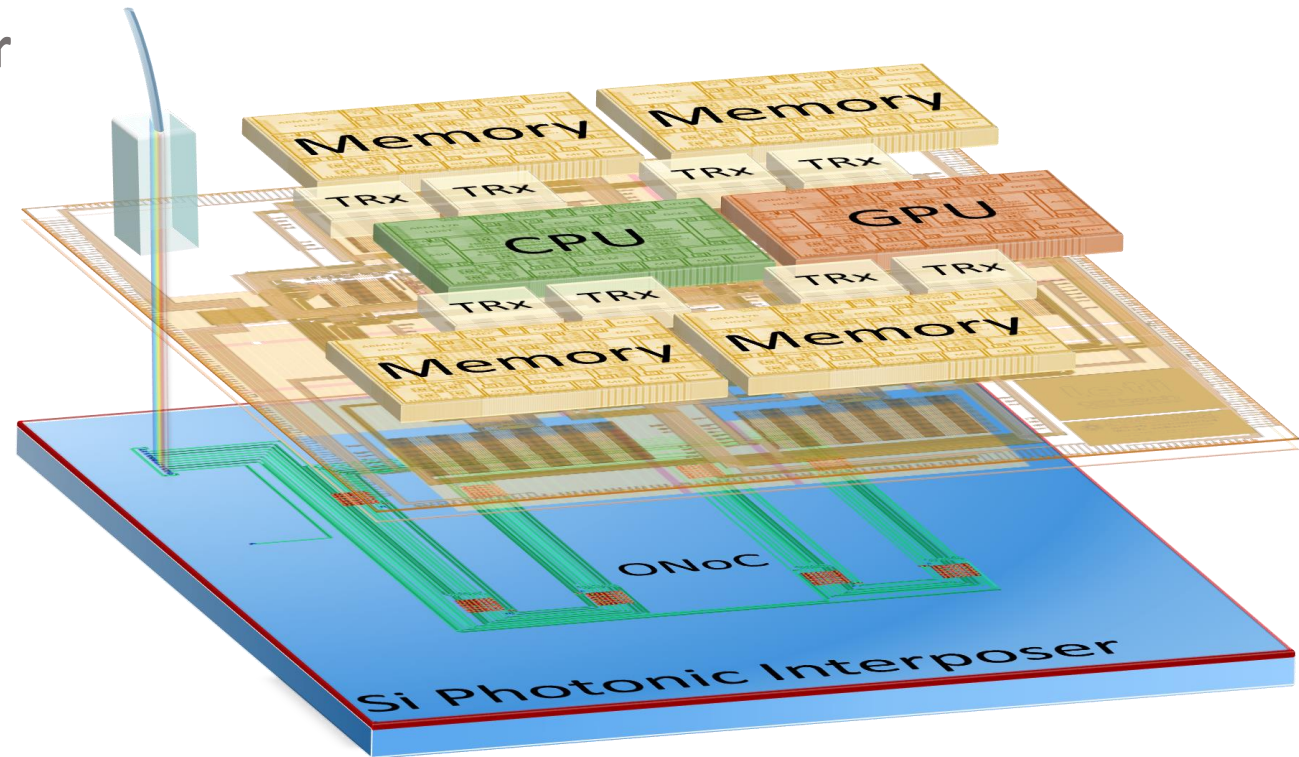
- 100 / 400 Gigabit Ethernet

► Large-scale electronics longs for low-latency low-energy dense communication

► Optical short-range communication has been a long-term target for years

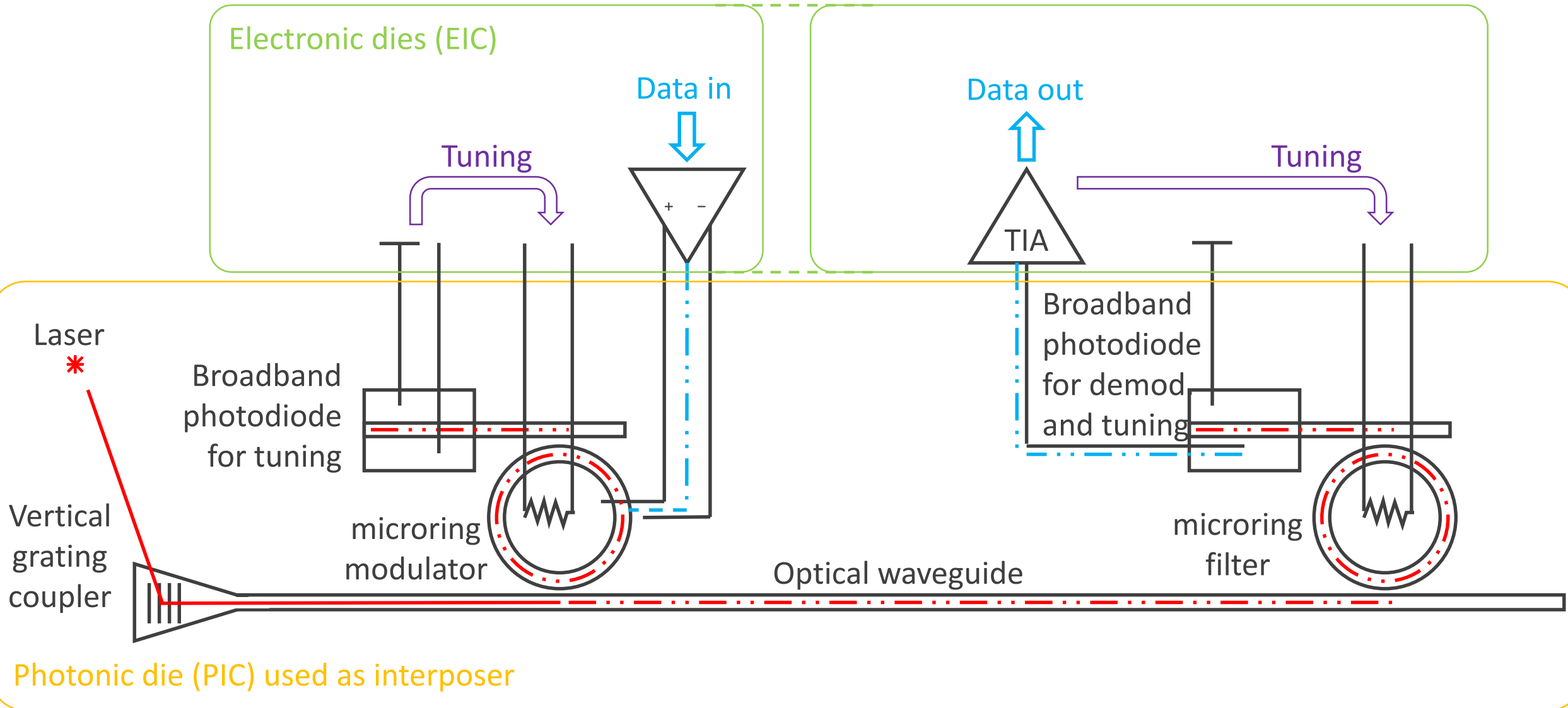
- Needs compact optical devices to maximize bandwidth per mm²

➔ Microring optical resonators



Optical Network on Chip

Microring modulator based link



► Compact optical devices

- Highly resonant: Q-factor 10,000–30,000

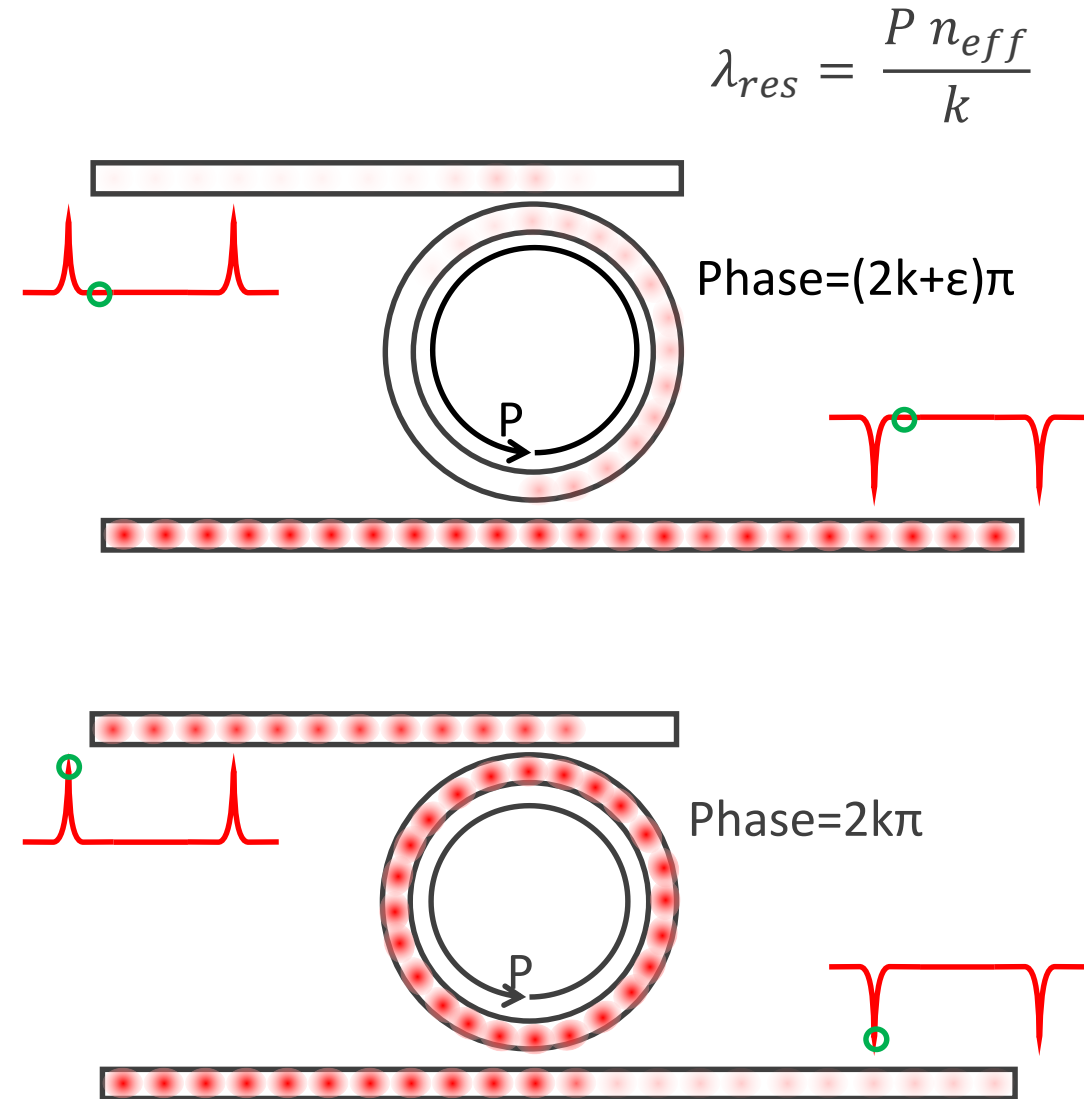
► Any refractive index change shifts the resonant wavelength

► PN or PIN diode junction can be created inside the ring for electrical control

- Different uses depending on diode
 - PN rings can be used as modulators (> 10 Gbps)
 - PIN rings can be used as filters (<500 MHz) for routing and wavelength demultiplexing

► But Subject to Temperature variations

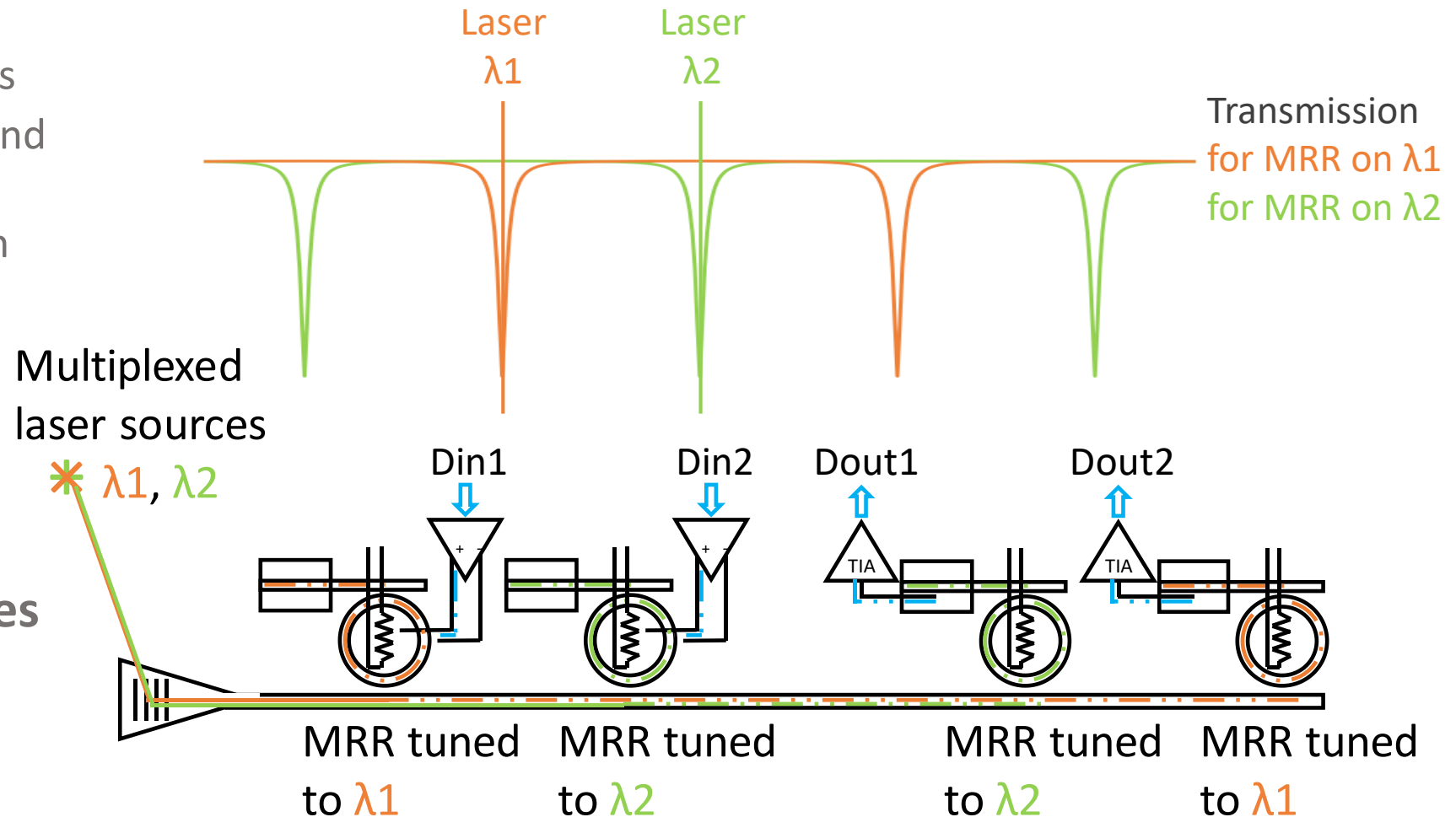
- ➔ Low-frequency resonance shift



► Narrow MRR resonances allow multiplexing

- Independent data streams
- Paired MRR modulators and filters per wavelength
- Additional MRR filters can be used for routing

► Different ONoC topologies can be derived from this base scheme



► High dependence on process variability

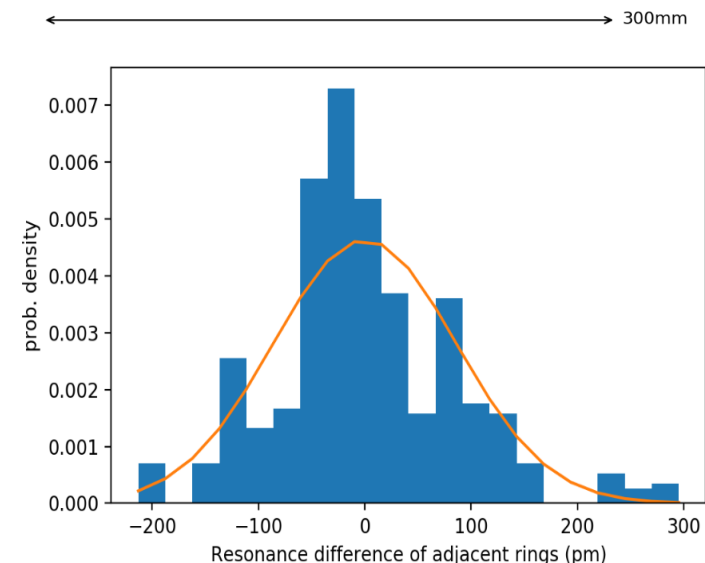
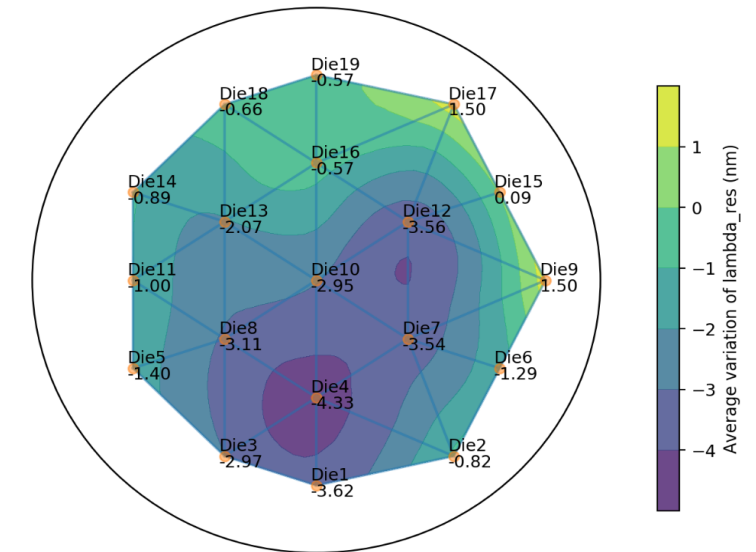
- MRR resonance can shift by about 1nm per nm of thickness

► Geometrical variability : wafer scale characterization

- Identical MRR resonances characterized around 1310nm
- FSR ~ 7.2 nm
- Variation of resonance across 5cm < 2nm in average
- Worst-case geometrical variation: **75pm/mm**

► Random variability : close identical rings

- Resonance difference of identical adjacent MRRs
- Random variation : standard deviation: **$\sigma=60$ pm**



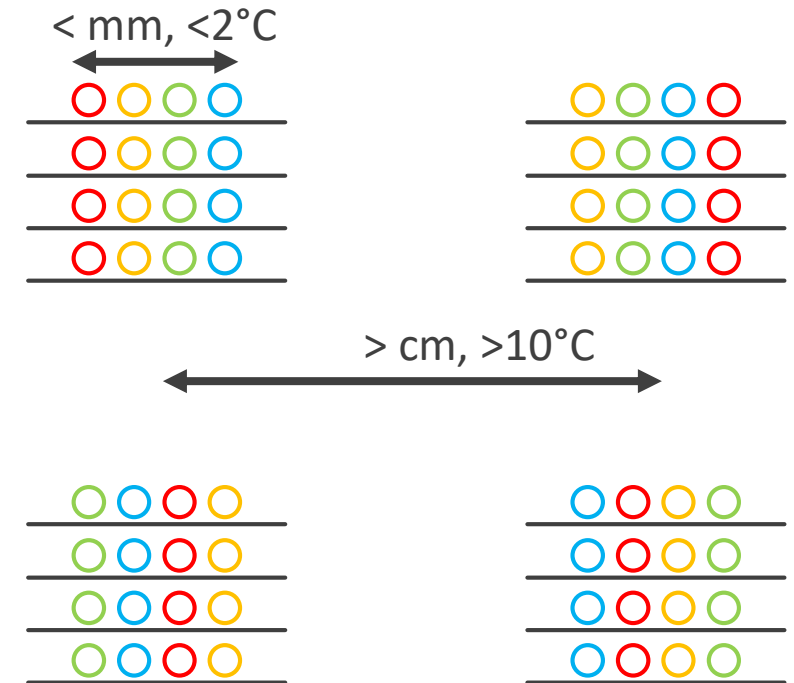
- Q-factors > 13,000 @ 1310nm => 3dB bandwidth < 100pm
- For **~0.1dB crosstalk** => ~7x margins+3 σ random variation
- up to **10-16 wavelengths** for 10nm FSR

► MRR groups within 1mm distance

- MRRs have little geometrical variability
- Local temperature effects are smoothed & almost uniform
- MRR groups operate consistently wrt wavelengths

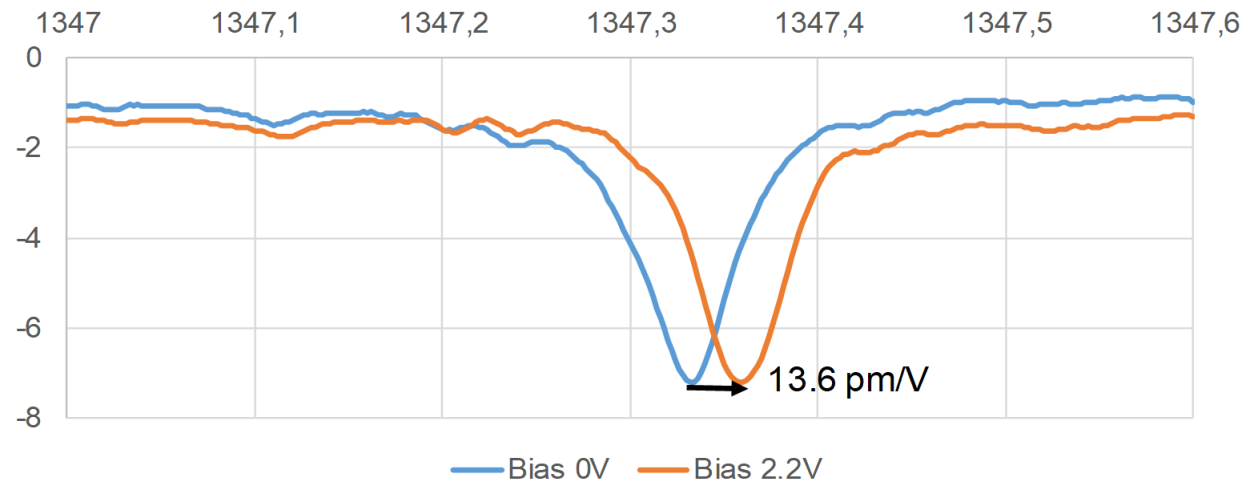
► Two MRR groups should have **no wavelength relationship**

- Geometrical variability becomes dominant in the cm range (>750pm)
- Temperature effects may show large local differences.

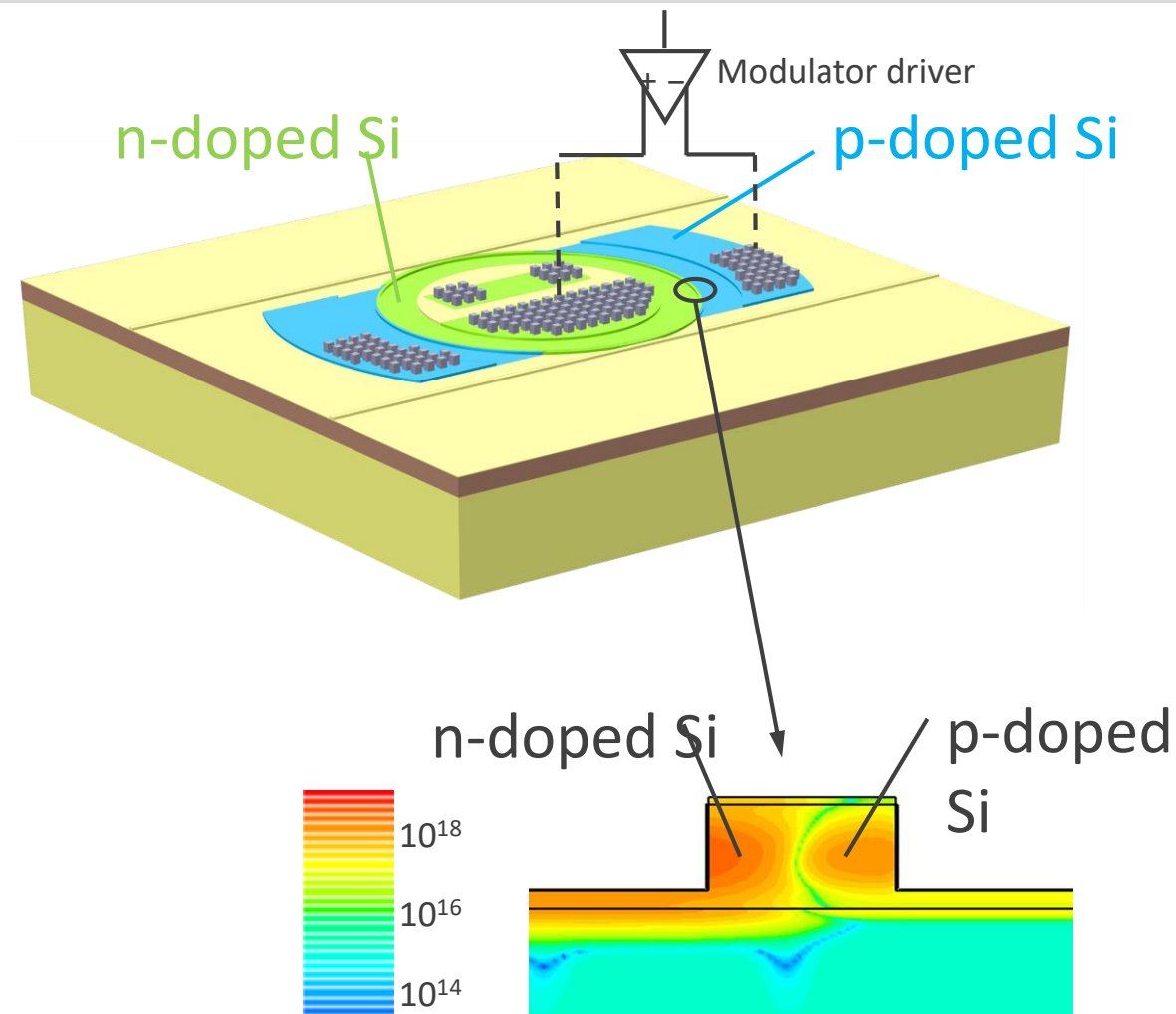
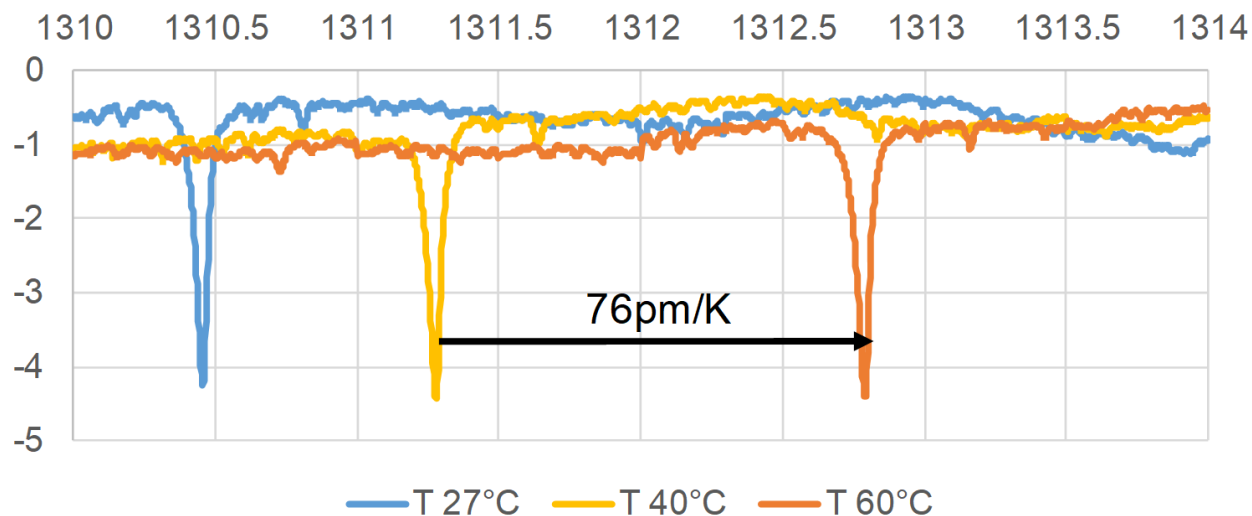


Modulator principle, Thermal sensitivity $d\lambda/dv$ & $d\lambda/dt$ measurements

► 13.6 pm/V modulation efficiency



► 76 pm/K thermal sensitivity

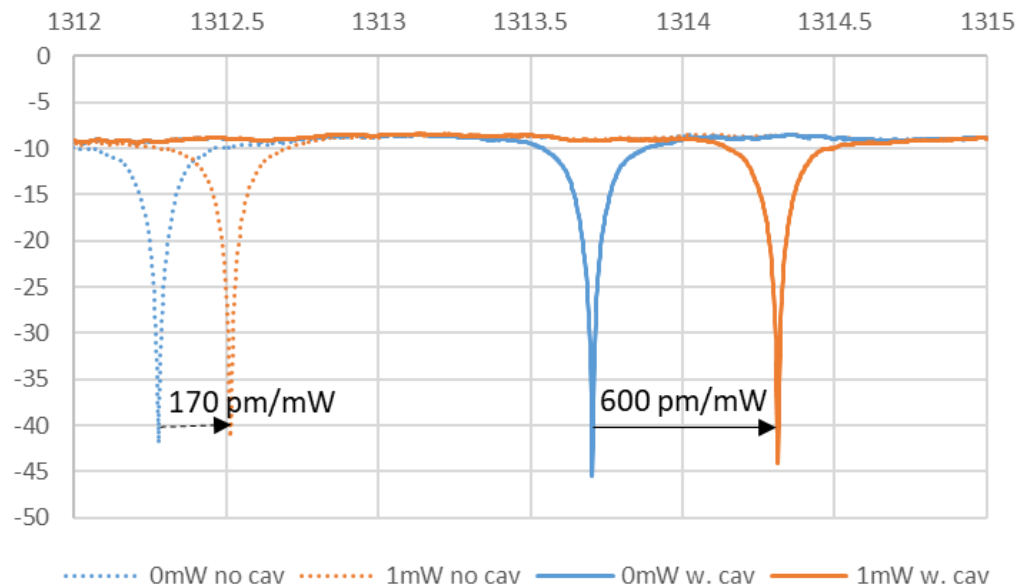


► Heating using a titanium loop resistor

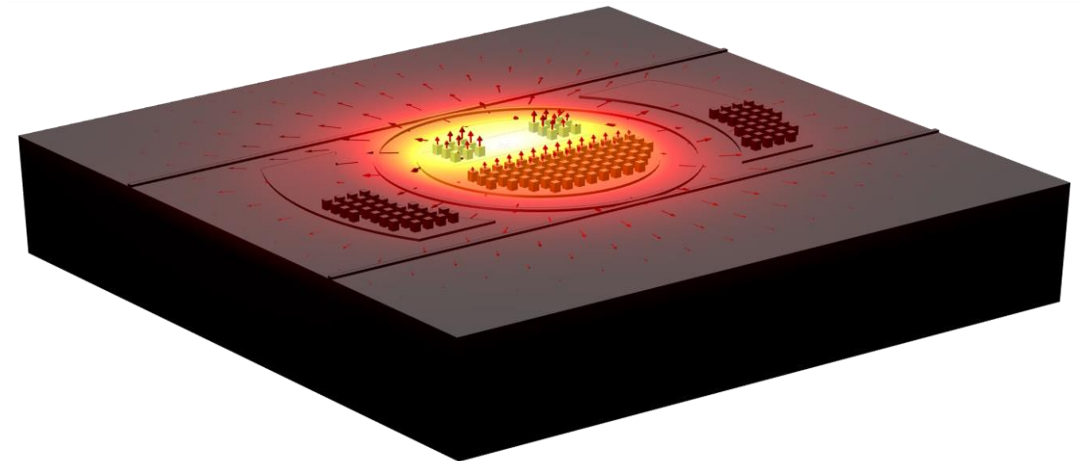
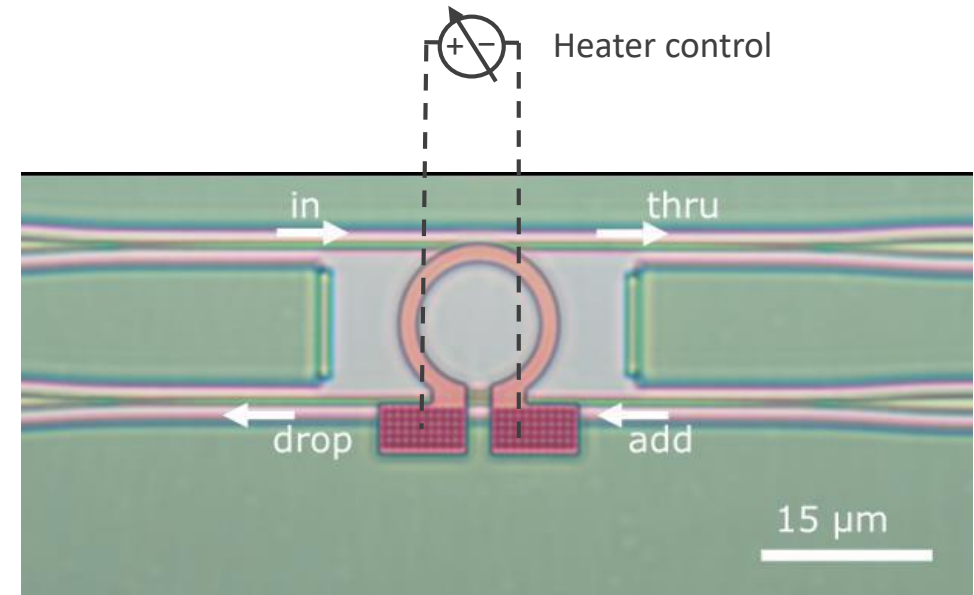
- 120 Ω Resistive path 900nm above the ring

► Average ring temperature increase:

- Measurements: $d\lambda/dP \sim 600\text{pm/mW}$



Temperature (K) and Heat Flux under 1mW heating



► Without cavity, heat flow from heater is mostly drained by substrate

- Efficiency limited to 170pm/mW

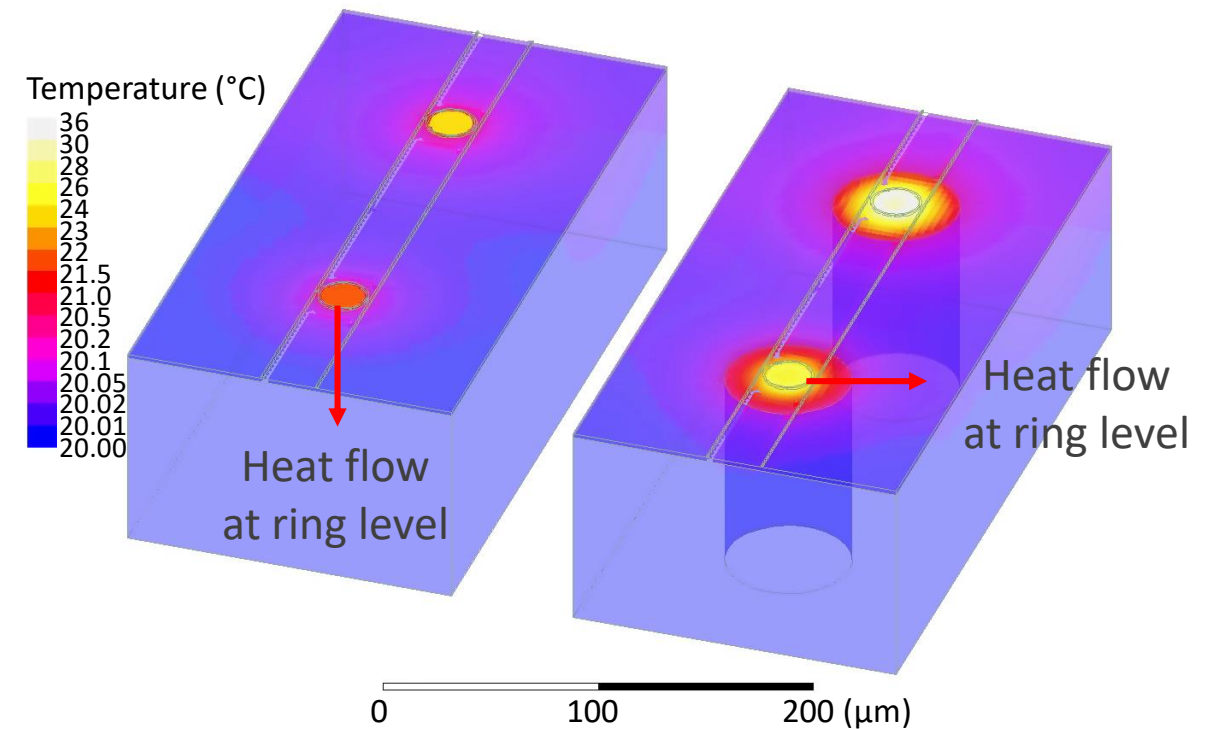
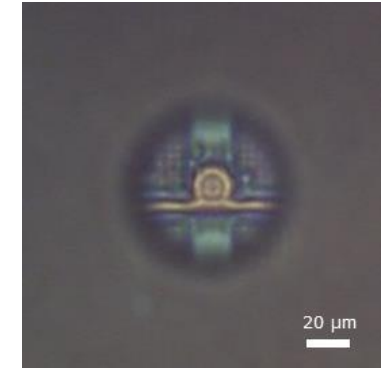
► Thermal tuning range extension by back-side substrate removal

- Back-side cavity allows extending to ~600pm/mW,
- i.e more than a quarter of FSR for 4mW

► Simulations show limited thermal coupling between adjacent rings: <1pm/mW

- Thermal crosstalk is not an issue

A ring seen from the back side cavity



► Ring resonant wavelength unpredictable at design time

- 1 nm thickness variation
≈ 1 nm resonance shift

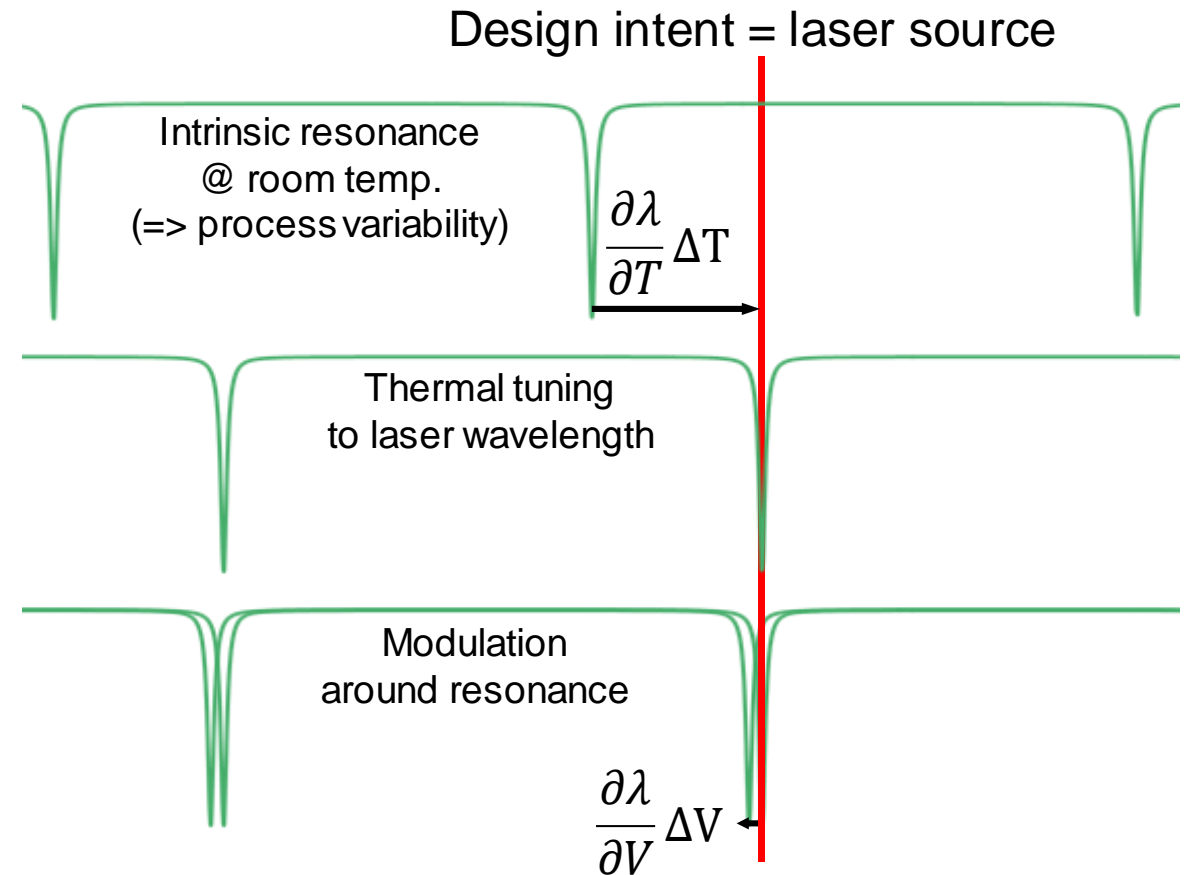
► But finesse, free-spectral-range & amplitudes are well-controlled

► Thermal tuning is used to align ring resonance on laser source

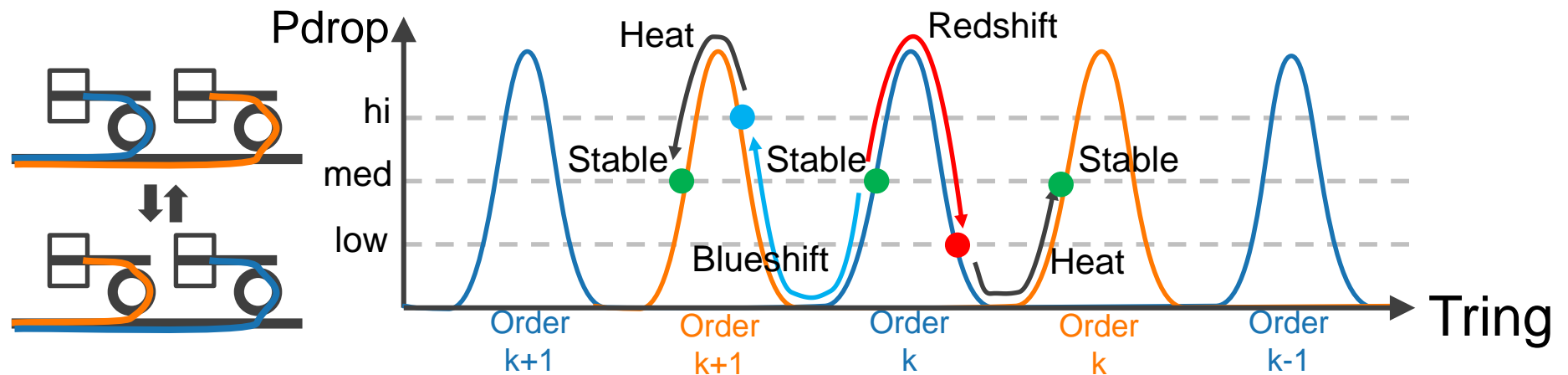
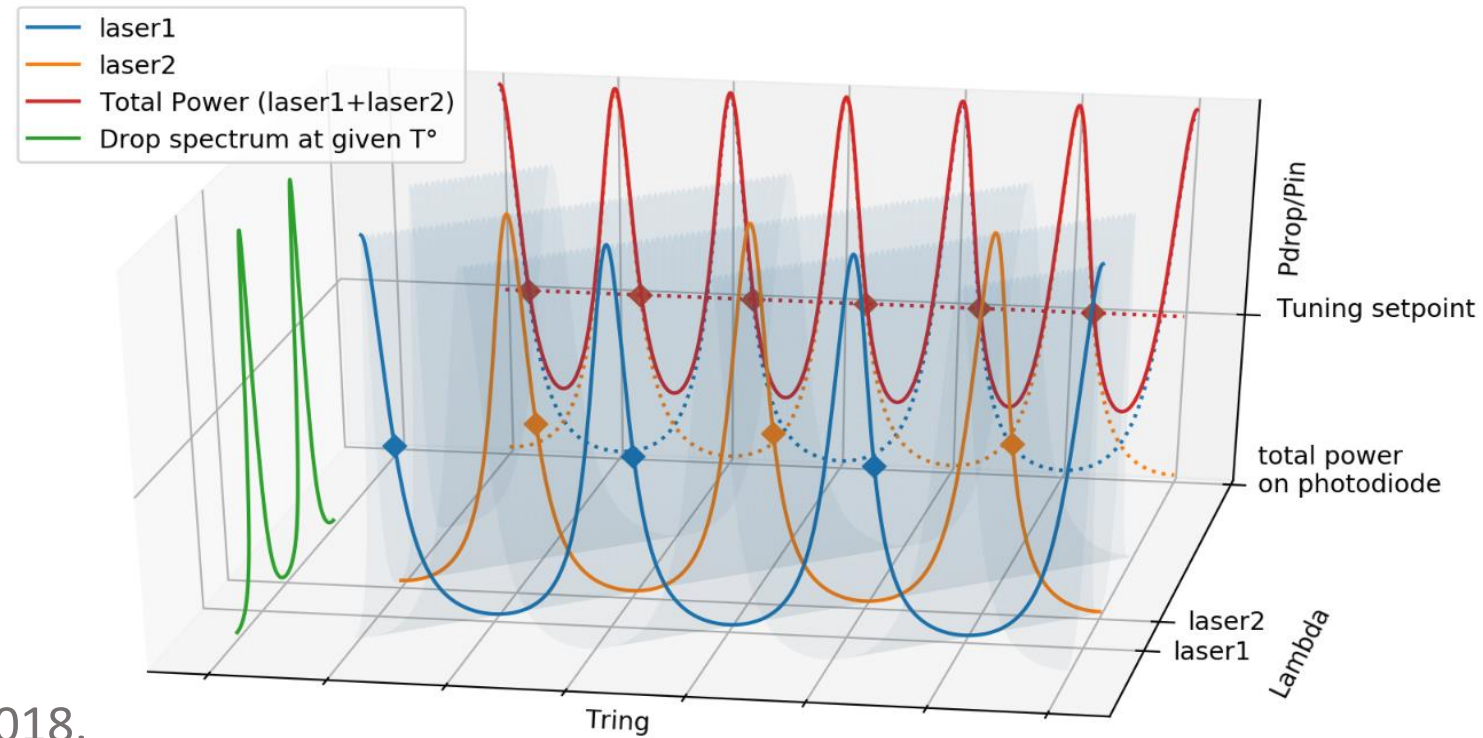
- Low-frequency control

► Voltage is used to modulate light

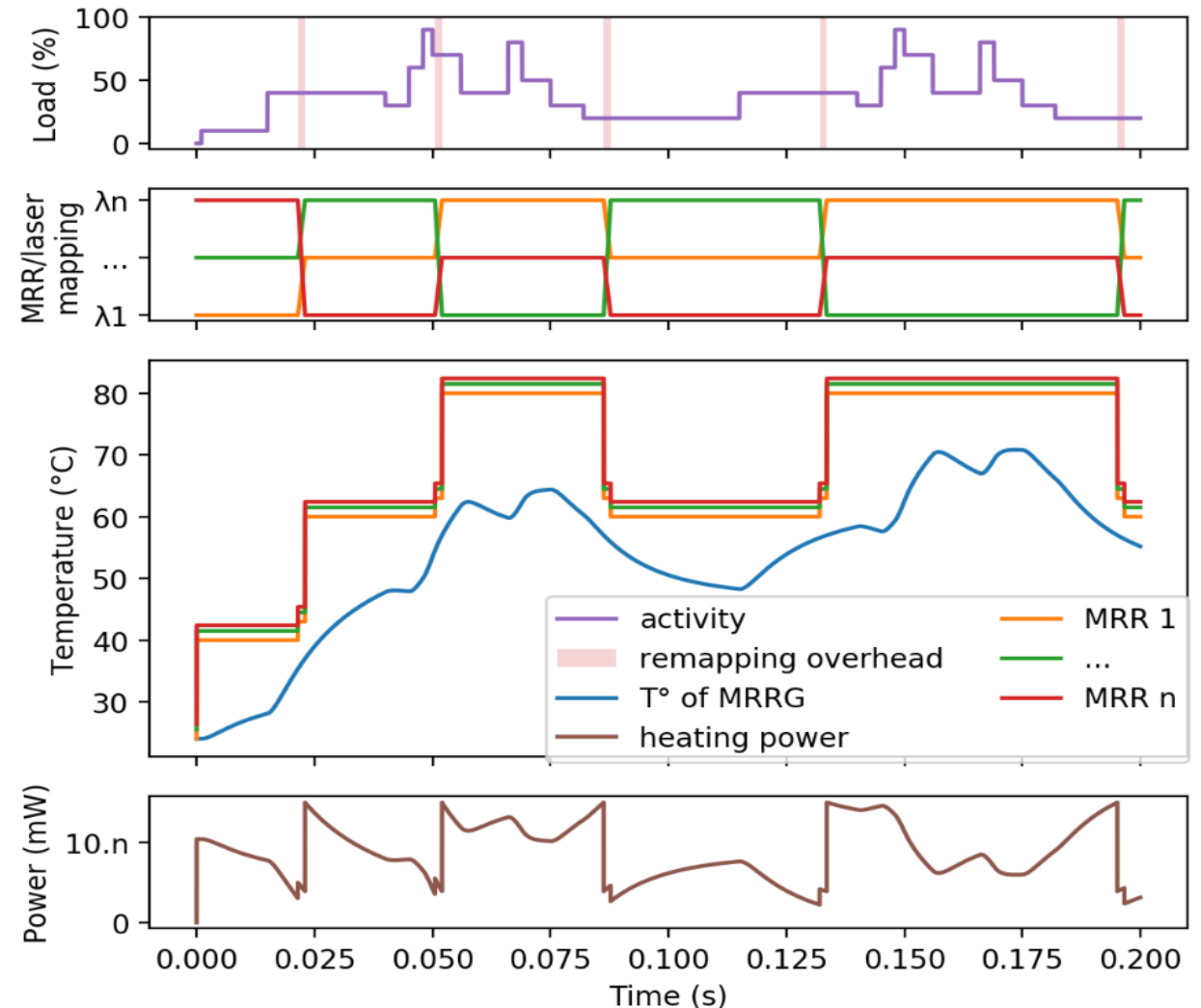
- High frequency modulation



- WDM reduces the maximum thermal shift to the closest resonance
- Closed-loop MRR tuning fixes the temperature to a stable modulation point
- Remapping occurs when ambient temperature varies too much
 - Details in [9] Thonnart et al., ISSCC, 2018.



- ▶ Activity load in compute chiplets creates local temperature increase
- ▶ Closed-loop control regulates Heater power for each MRR to lock to closest laser wavelength & maintain a constant MRR temperature
- ▶ When Heater power becomes too small, MRRs are remapped to lower λ
- ▶ When heater power becomes too high, MRRs are remapped to higher λ



► Rings with PN junction have a low switching time

- Suited for data modulation > 10 Gbps

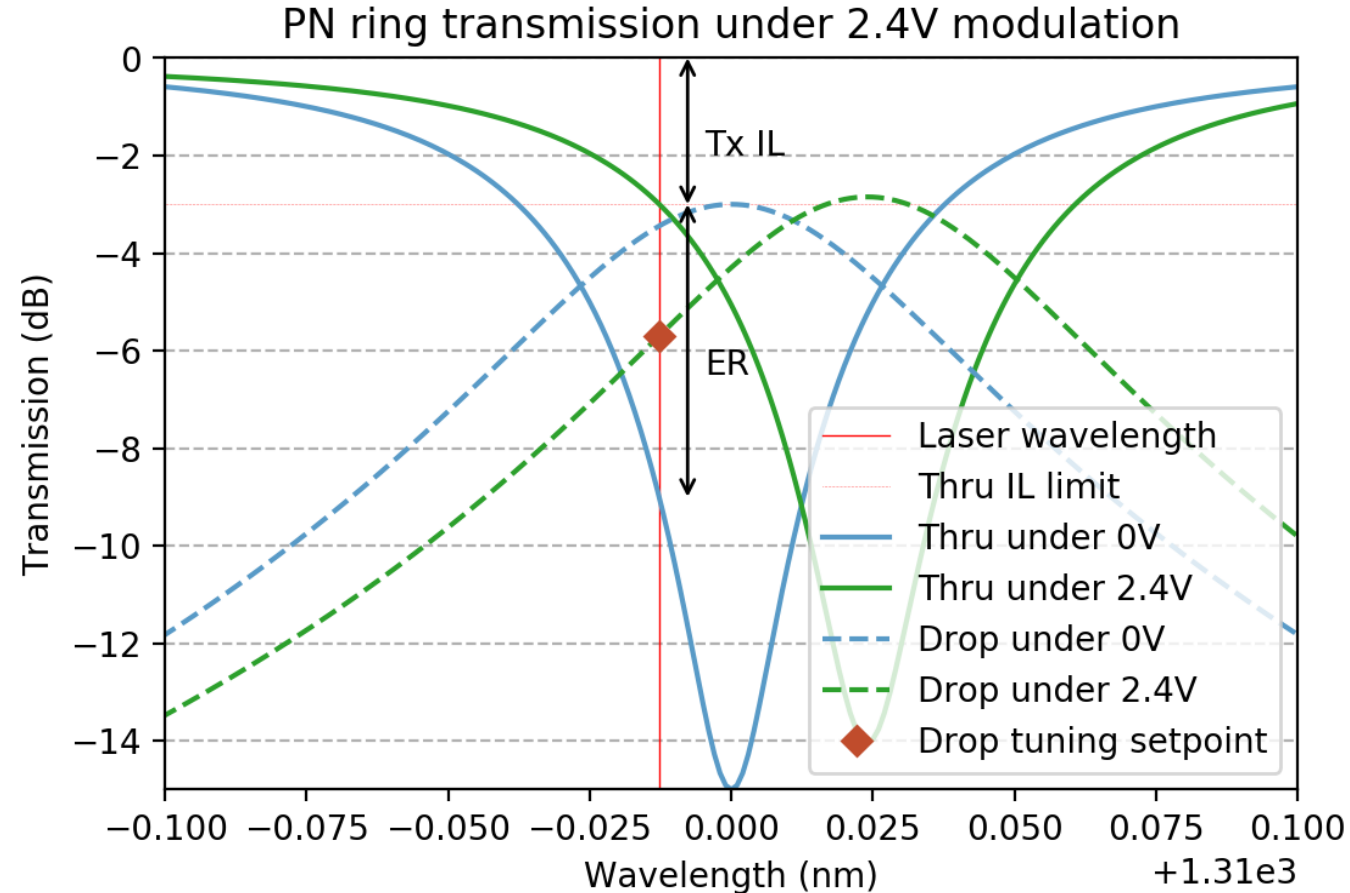
► But modulation efficiency remains low

- About 20% of bandwidth per volt

► Tradeoff to find between 'off' losses and extinction ratio

► Drop transmission correlated to peak extinction ratio

- Sufficient power required for tuning



► Rings with PIN junction have a higher modulation efficiency and higher drop transmission

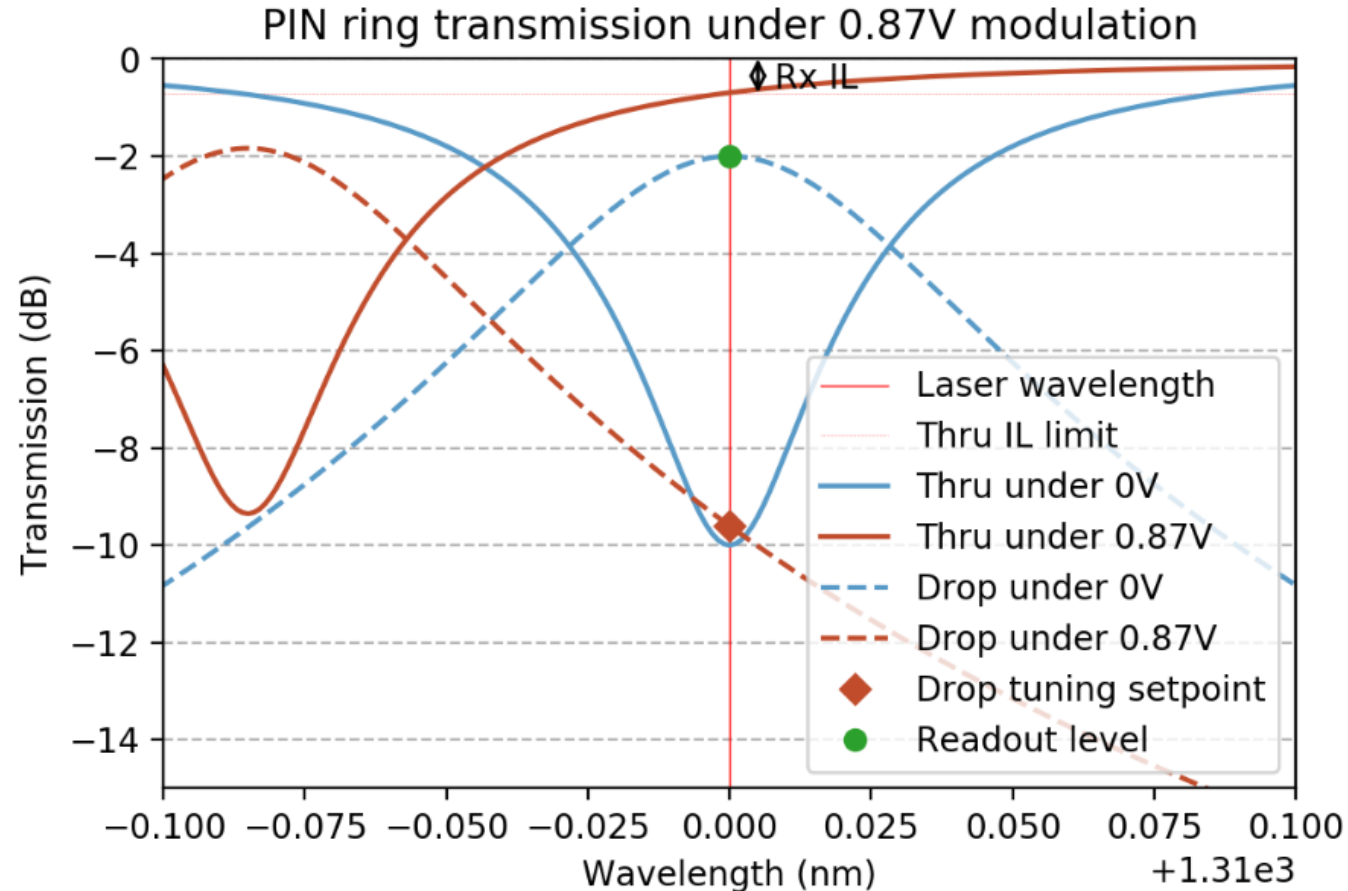
- Suited for data filtering

► But switching speed is limited

- About 200 MHz
- Higher with pre-emphasis

► Tradeoff to find between 'off' losses and 'off' drop transmission power

- Sufficient power required for tuning



Device	Parameter	Value
PN MRR modulator	Thru IL off-res. ("1")	-3dB
	Thru IL on-res ("0")	-9dB (ER 6dB)
	Drop IL tuning	-6dB
PIN MRR filter	Thru IL off-res. (deselected)	-0.7dB
	Drop IL on-res (selected)	-2dB
	Drop IL tuning	-10dB
Waveguide	Straight losses	-0.11dB/cm
	Critical radius (lossless)	20 μ m
	Crossings (1x1 MMI)	-0.25dB
Grating coupler	IL	-2dB
Laser power	Max power in MRR	3dBm
O/E sensitivity	Demod. sensitivity (10Gbps)	-15dBm
	Tuning sensitivity	-18dBm

► Limit the number of rings on an optical path

- Due to insertion losses

► Limit as much as possible the number of « crossings », i.e. drop paths

- Due to drop losses
- Favor single waveguide transmission

► Favor PIN over PN on link budget

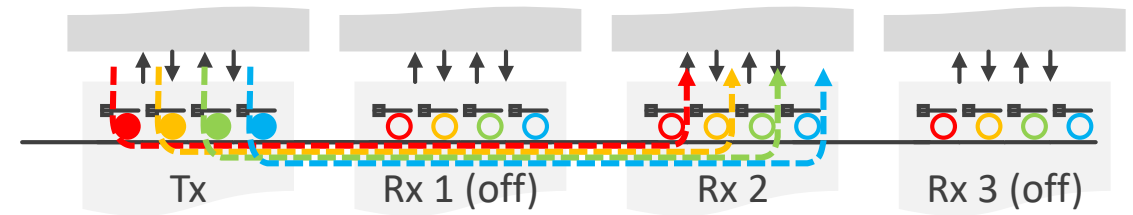
- Because of lower insertion losses

► Consequently, use SWMR topology

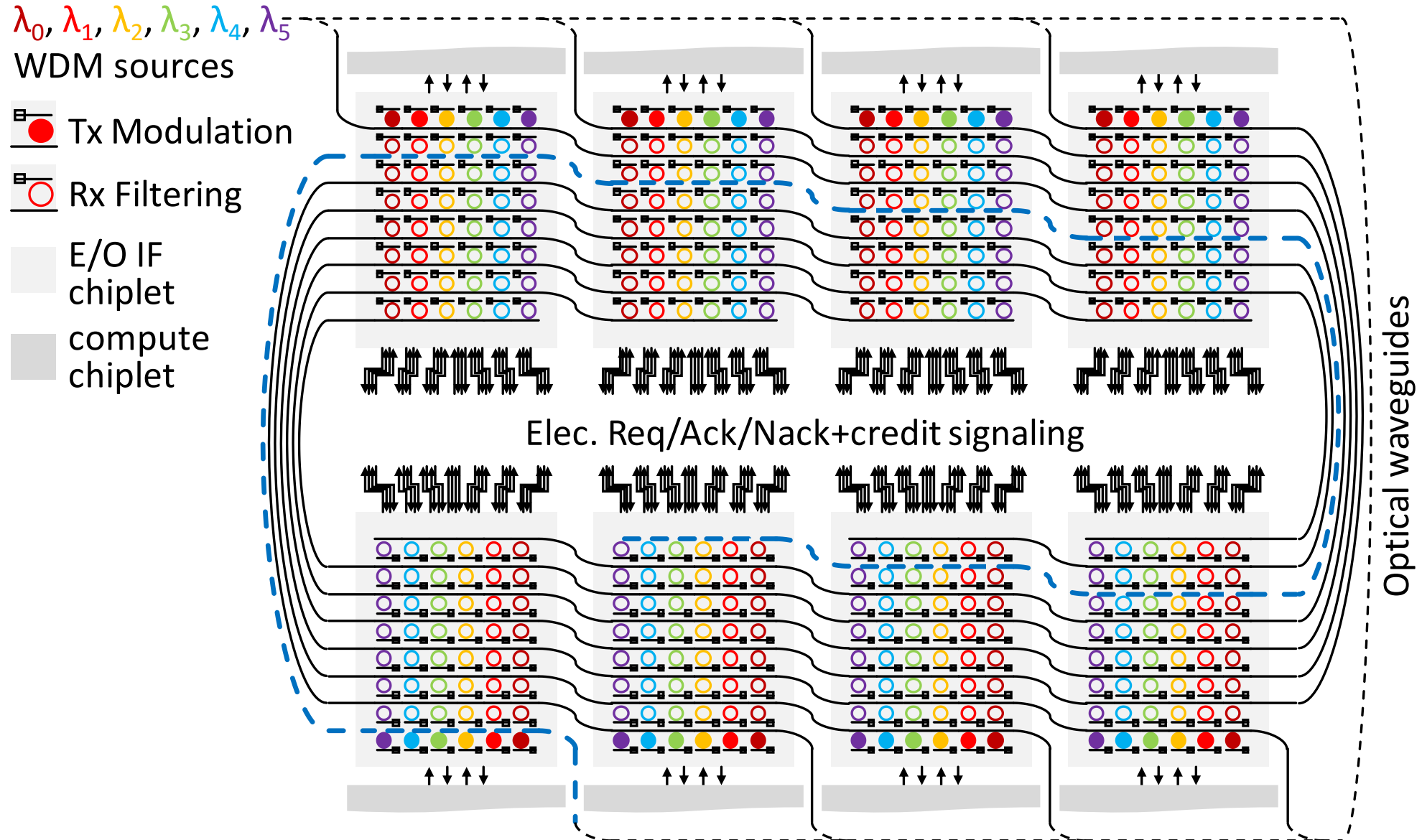
- PN rings at Tx, PIN rings at Rxes

► Use all WDM wavelengths as a single data bus

- No wavevength routing
- To limit the remapping overhead
- To avoid global communication synchronization
- To enable decentralized local arbitration



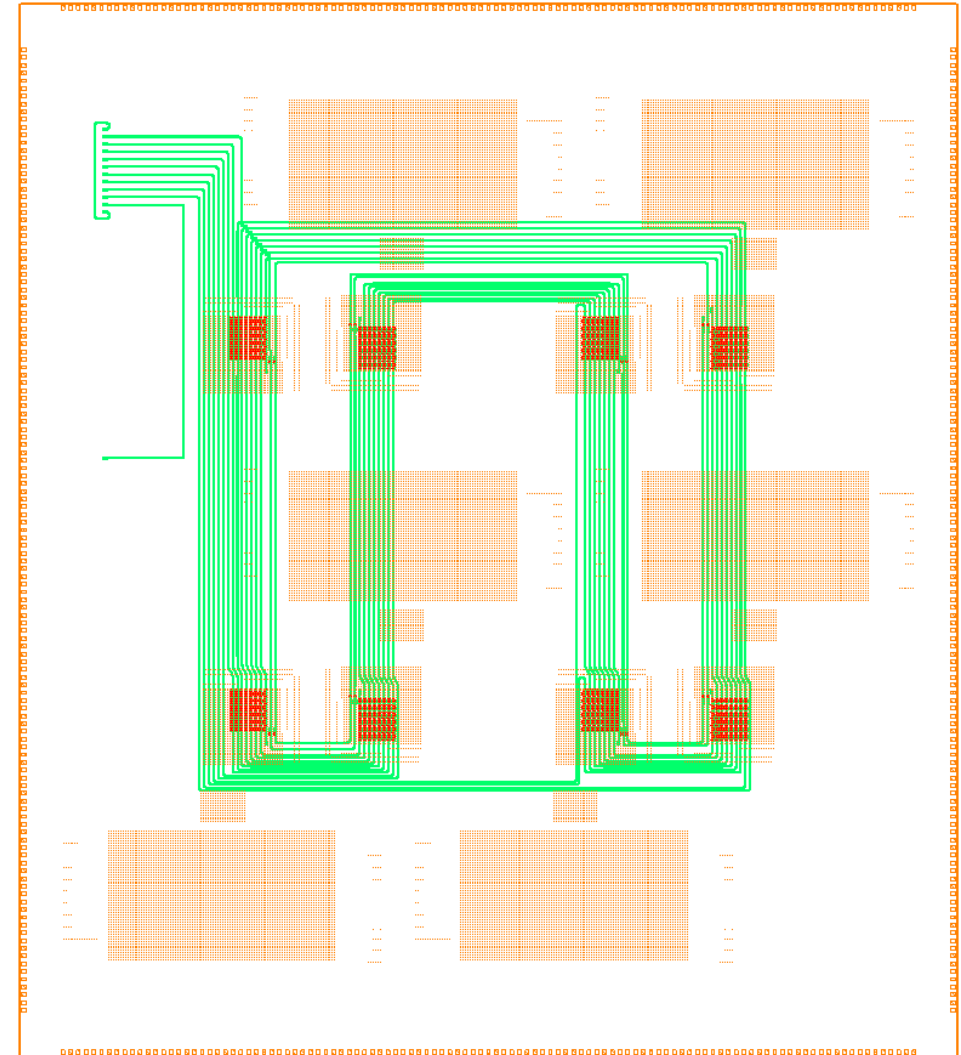
POPSTAR photonic interposer electro-optical architecture



► An 8-port POPSTAR instance on a folded ring

- 6 wavelengths are used for each channel
- 384 microrings in total
- Up to 1Tbyte/s @ 12GBaud aggregate bandwidth

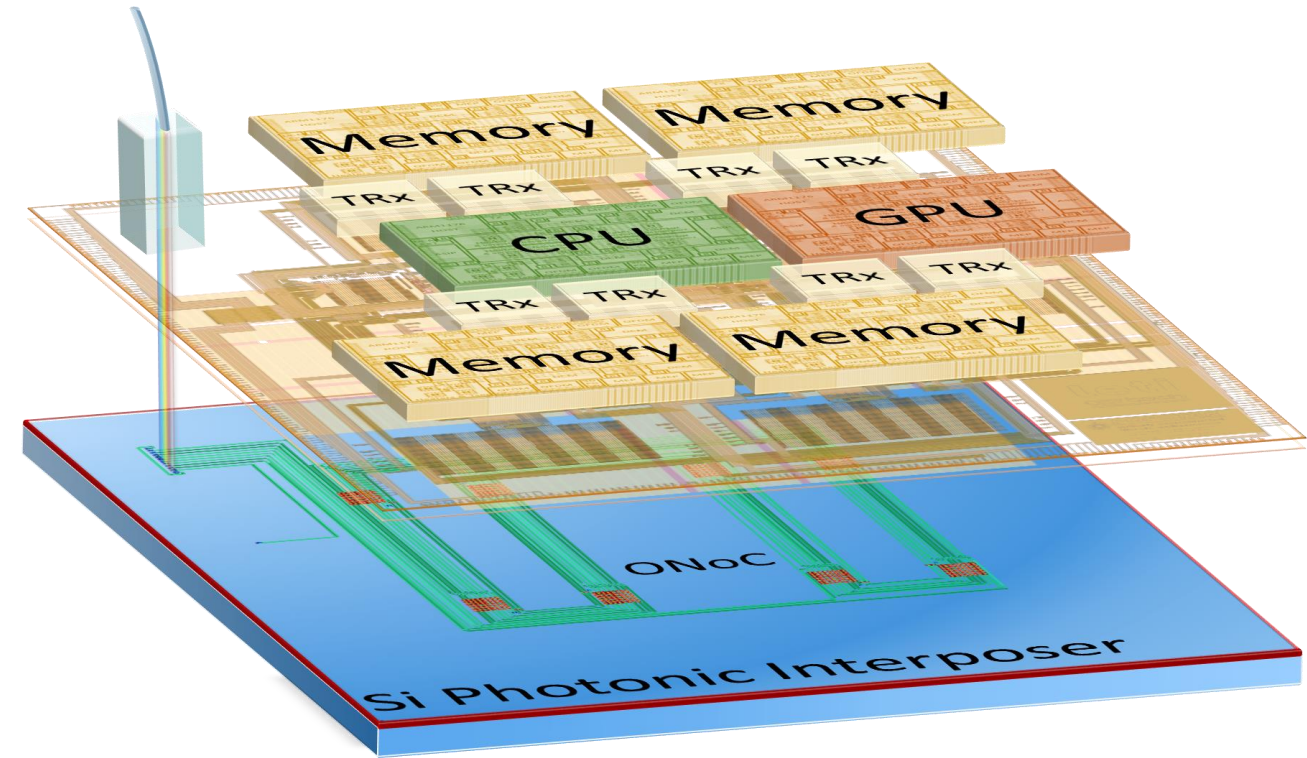
► 6 compute chiplets, 2 external IO interfaces



► An 8-port POPSTAR instance on a folded ring

- 6 wavelengths are used for each channel
- 384 microrings in total
- Up to 1Tbyte/s @ 12GBaud aggregate bandwidth

► 6 compute chiplets, 2 external IO interfaces



► A single Tx IL

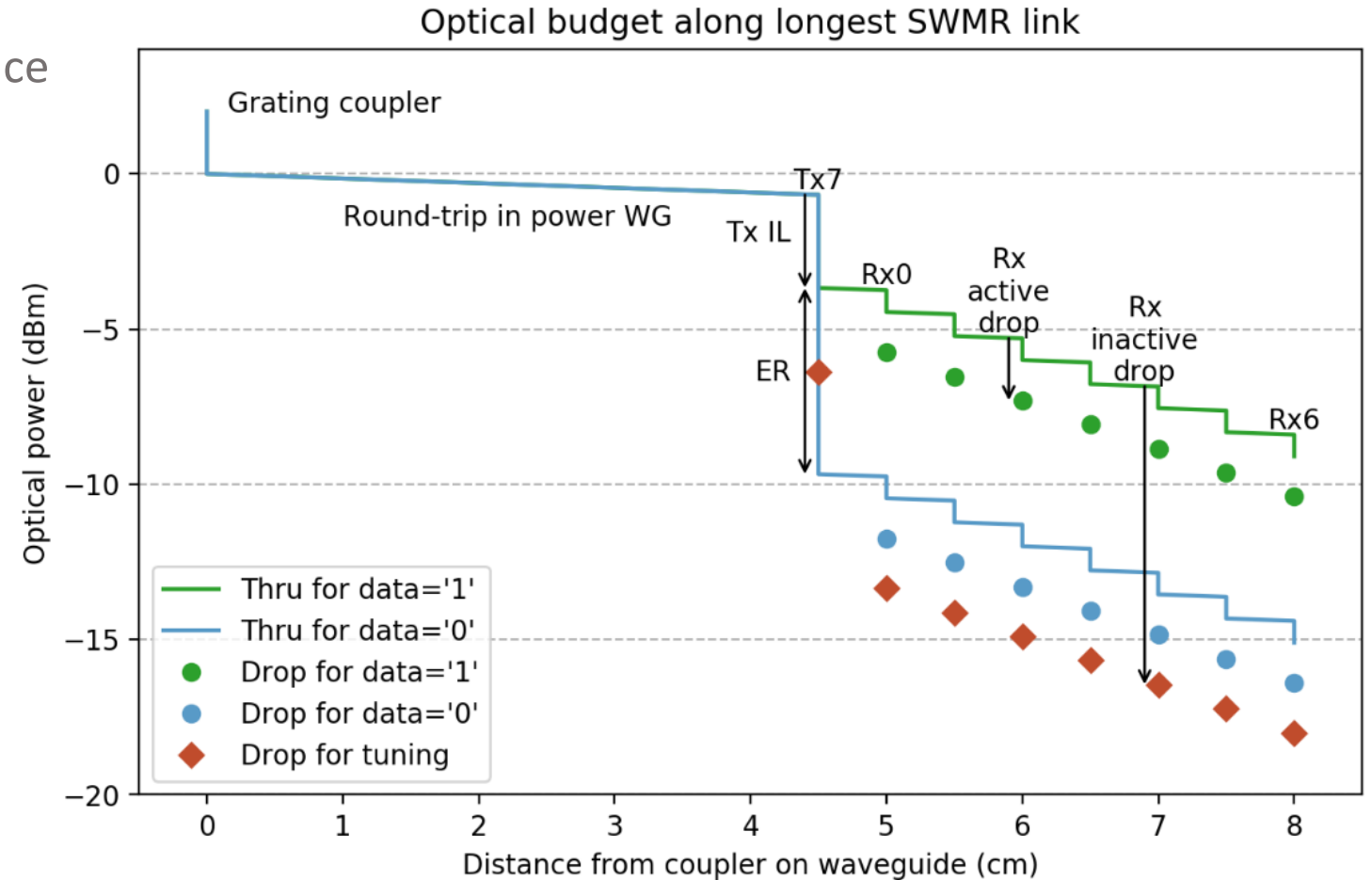
- Tuning on drop port close to resonance

► A series of inactive Rxes

- Tuning for low IL

► Low drop losses on active Rx

- Graph shows 0 and 1 levels based on Tx modulated data



► Data preamble for channel setup

- Optical 1010101011 sequence
- Low-level synchronization
- Wavelength identification

► End-to-end flow-control

- Using low-latency metal signaling

► Req/Ack/Nack protocol

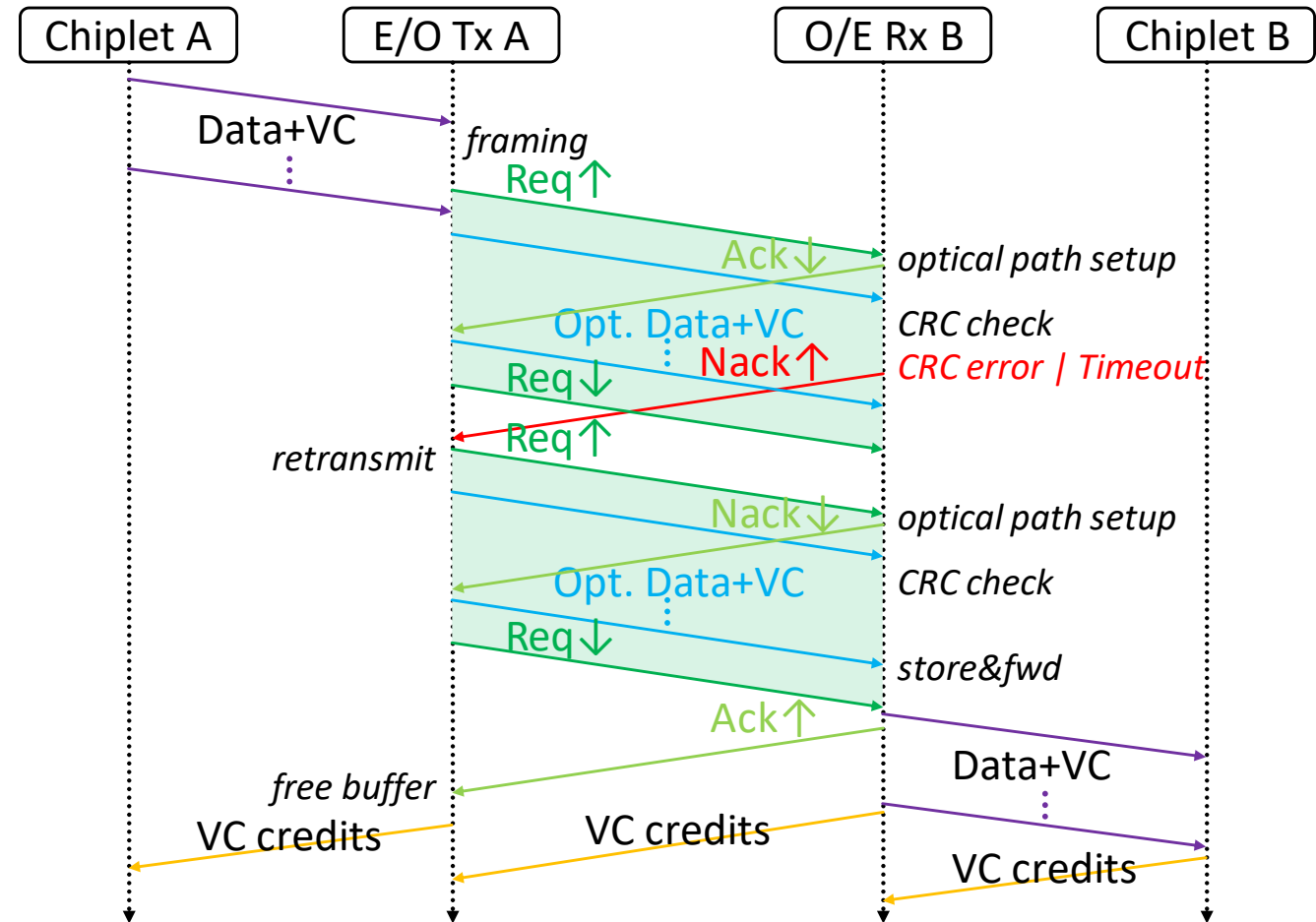
- Optical CRC encoded in the data
- Possible retransmission
- Store & Forward to Compute chiplets

► Credits for low-latency

- Receiver always ready to receive

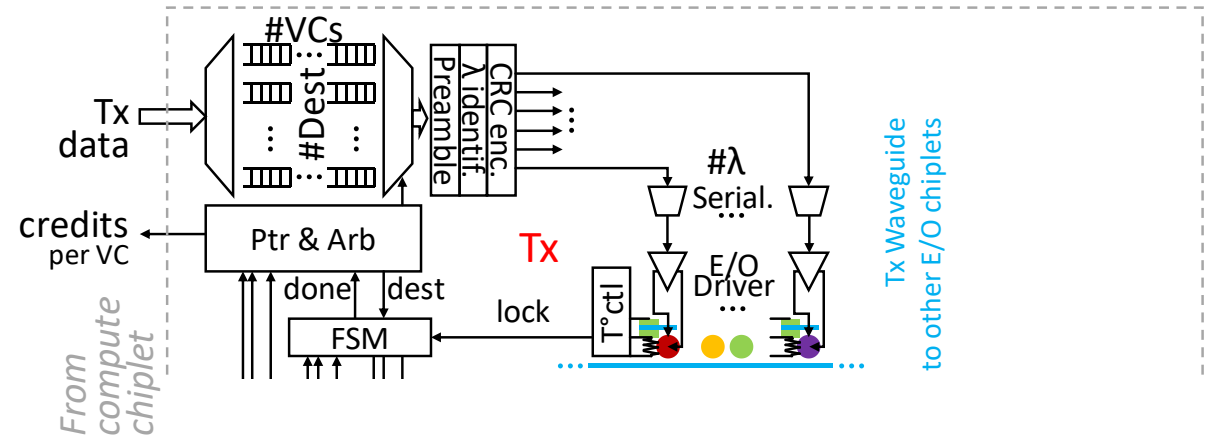
► Virtualization of traffic classes

- Virtual channels for credits & S&F buffers



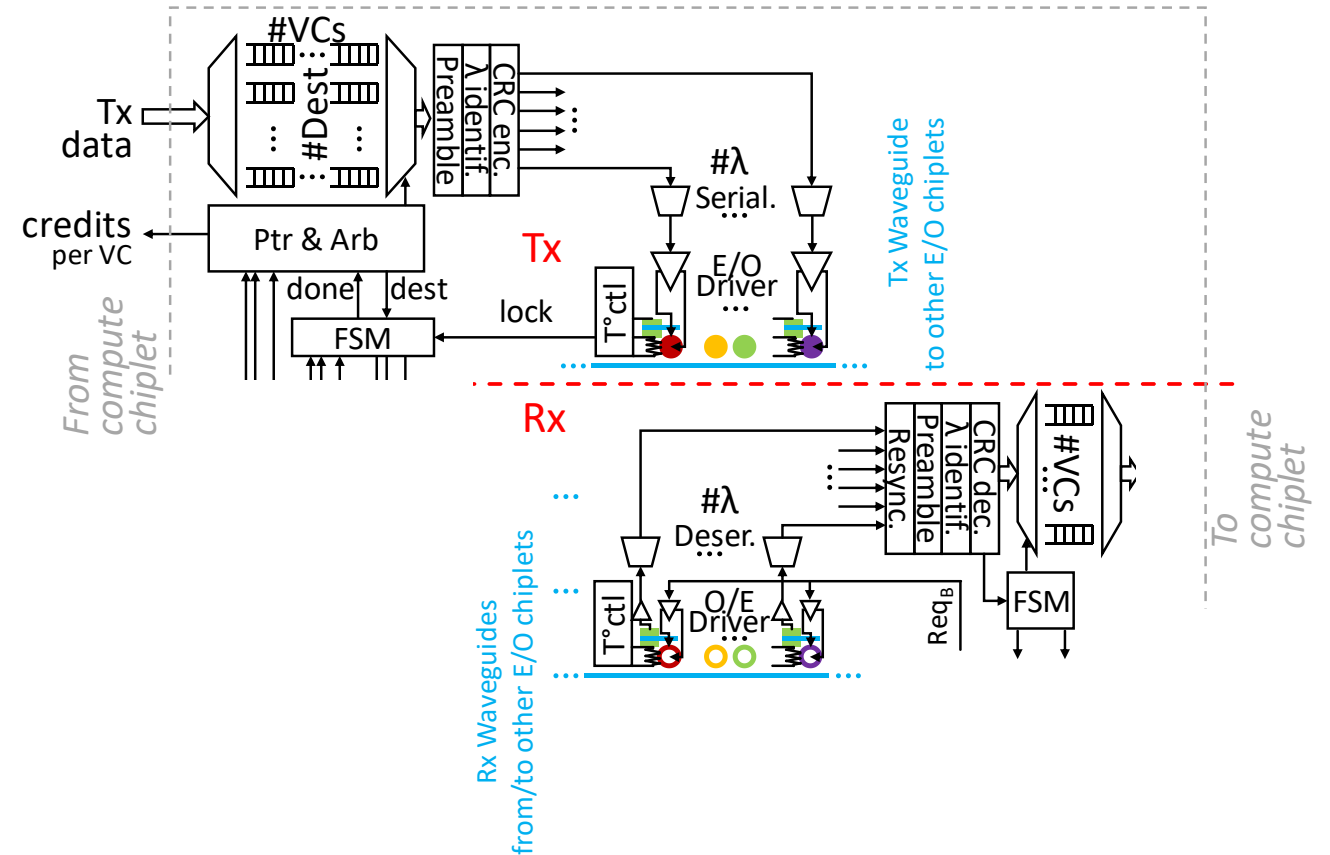
► Tx architecture

- VC buffering
- Flow control based on credits
- Preamble encoding
- Wavelength identification
- CRC encoding
- Serialization
- E/O driving
- Thermal tuning

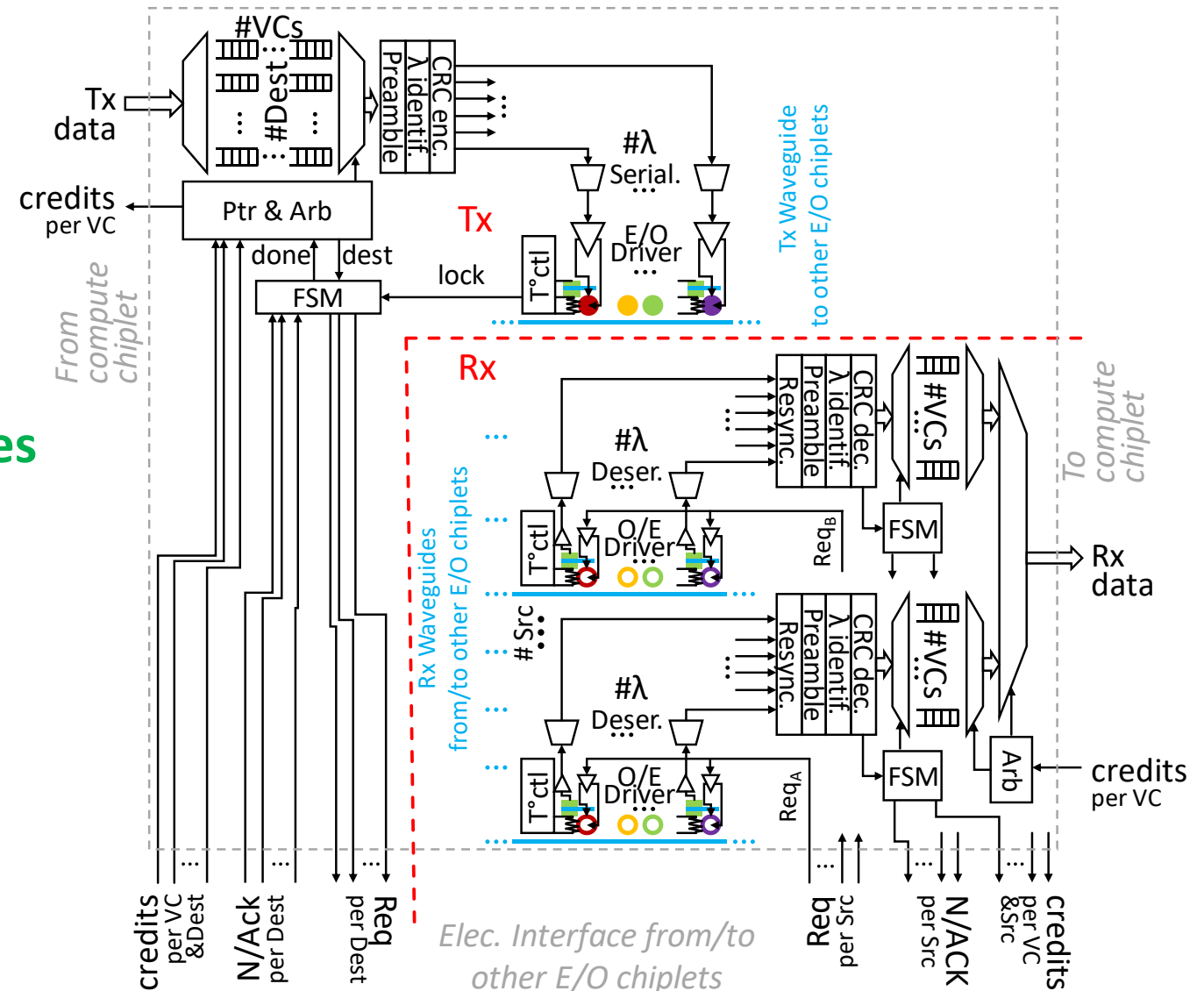


► Rx architecture

- O/E demodulation
- Thermal tuning
- Deserialization
- Resynchronization
- Preamble decoding
- Wavelength identification
- CRC decoding
- VC buffering
- Flow control based on credits



- Arbitration between different Txes on separate Rx channels
- Req/Ack/Nack for each pair of Tx-Rx
- Minimum end-to-end latency: **12 cycles**
 - Can be higher with S&F & queuing



- ▶ **POPSTAR: a robust modular architecture for E/O communication between chiplets on a photonic interposer**
 - Based on technological constraints
 - To cope with process and thermal variability
 - Independent SWMR links for coordinated WDM remapping
- ▶ **A standard replicable E/O chiplet to interface with compute chiplets**
 - In charge of routing, flow-control and arbitration
 - Low-latency non-blocking distributed crossbar
 - Arbitration contained in Rx chiplets without in-network contention
- ▶ **Low-latency communication for large-scale chiplet-based 3D systems**
 - New architecture opportunities for data-intensive high-performance applications